

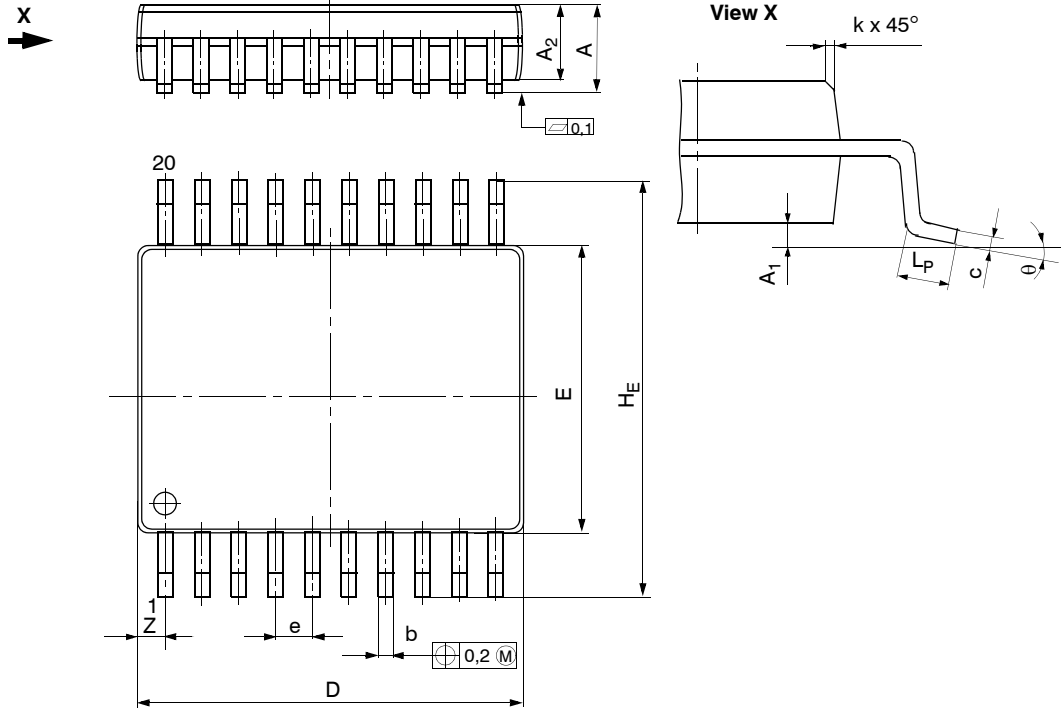

Package SOP20
 (300 mil)

MDS
727

 Supersedes
 Edition 01.95

Dimensions in millimetres

Based on IEC 191-2Q: Type 075E04 B

1 Dimensions

Dimensions of Sub-Group B1	
A_{\max}	2,65
$b_{P\min}$	0,35
$b_{P\max}$	0,49
e_{nom}	1,27
$H_{E\min}$	10,00
$H_{E\max}$	10,65
$L_{P\min}$	0,40
Z_{\max}	0,81

Dimensions of Sub-Group C1	
A_{\min}	2,35
$A_{1\min}$	0,10
$A_{1\max}$	0,30
$A_{2\min}$	2,25
$A_{2\max}$	2,45
c_{\min}	0,23
c_{\max}	0,32
D_{\min}^*	12,60
D_{\max}^*	13,00
E_{\min}^*	7,40
E_{\max}^*	7,60
k_{\min}	0,25
θ_{\min}	0°
θ_{\max}	8°

- 2 Weight** $\leq 0,55$ g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

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